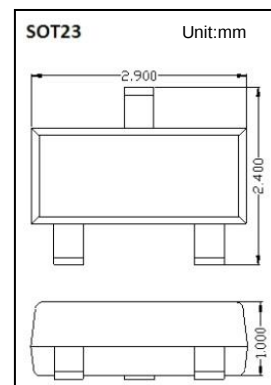


Schottky Barrier DIODE / DATA SHEET

BAS70---BAS70-06

- ◇ High Conductance
- ◇ Low Current Leakage
- ◇ Small Outline Surface Mount Package
- ◇ RoHS compliant / Green EMC

Device	Device Marking	Type	Pin Configuration See page 2
BAS70	73	Single	Figure1
BAS70-04	74	Dual	Figure2
BAS70-05	75	Dual	Figure3
BAS70-06	76	Dual	Figure4

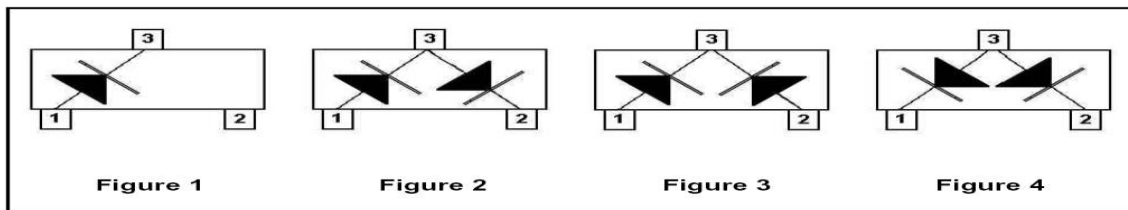


Maximum Ratings (Ta = 25 °C)

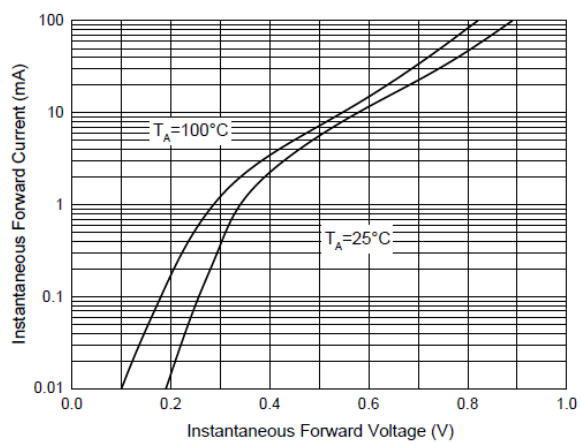
Symbol	Parameter	Value	Units
V_R	Reverse Voltage	70	V
I_F	Forward Continuous Current	70	mA
P_{tot}	Power Dissipation	200	mW
T_J	Operating Junction Temperature Range	125	°C
I_{FSM}	Peak Forward Surge Current (t=1S.NON-Repetitive)	0.1	A
T_{stg}	Storage Temperature Rance	-55 to 150	°C
T_j	Soldering temperature during	260	°C
R_j	Thermal Resistance Junction to Ambient	430	°C/W

Electrical Characteristics (Ta = 25 °C)

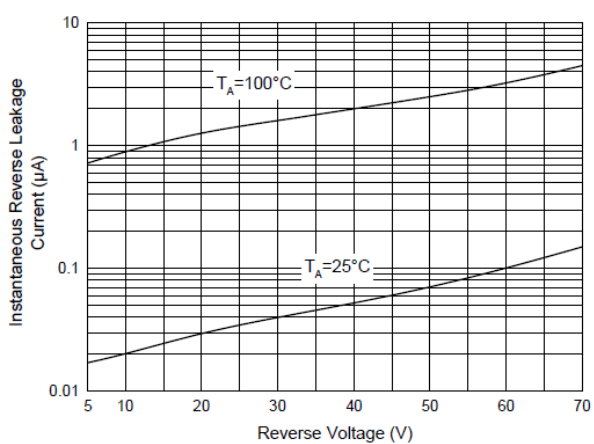
Symbol	Parameter	Test Conditions	Min	Max	Units
V_F	Forward Voltage	$I_F=1mA$ $I_F=15mA$		0.41 1.0	V
V_R	Reverse breakdown voltage	$I_R=10uA$	70		V
I_R	Reverse voltage leakage current	$V_R=50V$		100	nA
C_J	Typical Junction Capacitance	$V_R=0V, f=1.0MHz$		2	pF
T_{rr}	Reverse recovery time	$I_F=I_R=10mA, I_{(REC)}=1mA$		5	nS



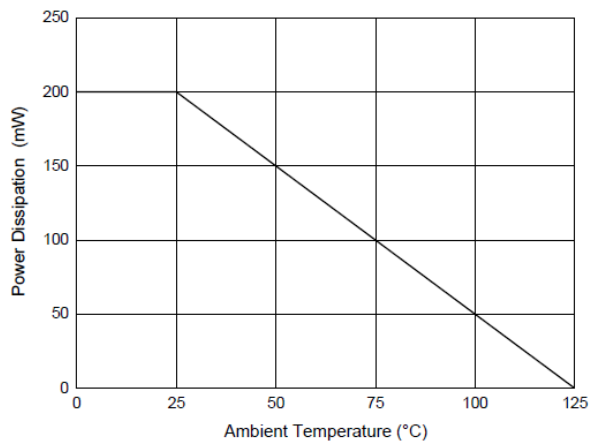
Typical Characteristics



Typical Instantaneous Forward Characteristics



Typical Reverse Leakage Characteristics



Power Derating Curve

Ordering Information

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
BAS70--- BAS70-06	SOT23	Tape & Reel 3000pcs /7" Reel	8mm	4mm	Conductive	

Package Dimensions

Package outline : SOT23

The diagram shows three views of the SOT23 package: a top view, a side view, and an isometric view. The top view shows dimensions A (total width), B (total height), C (body height), D (body width), E (pitch), and F (lead width). The side view shows dimensions H (body height), K (lead height), and L (lead length). The isometric view shows the package with dimensions J (lead thickness) and L (lead length).

Symbol	Dimensions in mm	
	Min.	Max.
A	2.800	3.040
B	2.100	2.640
C	1.200	1.400
D	0.890	1.030
E	1.780	2.050
F	0.450	0.600
G	0.013	0.100
H	0.900	1.110
J	0.085	0.180
K	0.370	0.510
L	0.300	0.500

SOT23 Package Outline

The diagram shows the SOT23 package outline with dimensions: 0.800, 0.900, 2.000, and 1.900.

Land Pattern Recommendation

Notice:

- 1.Lead plating: Pb free solder
- 2.Lead thickness includes solder plating
- 3.Lead frame: CAC-5
- 4.Other Tolerance: ± 0.05

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- 1.Lead plating: Pb free solder
- 2.Lead thickness includes solder plating
- 3.Lead frame: CAC-5
- 4.Other Tolerance: ± 0.05

NOTICE

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